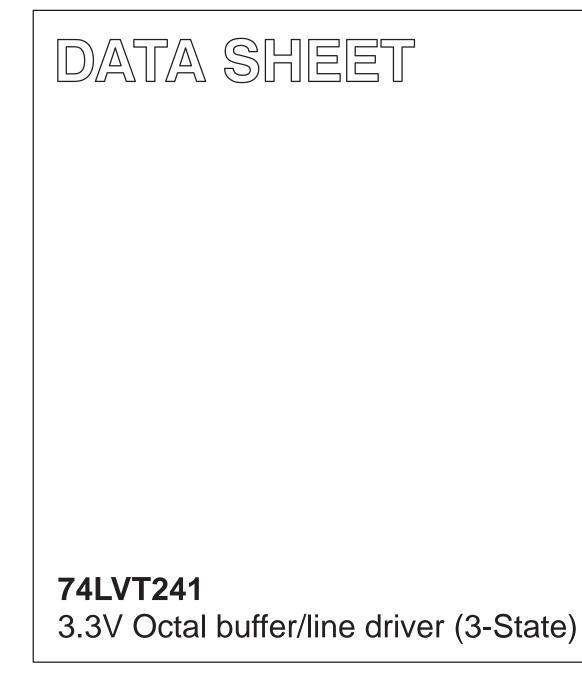
INTEGRATED CIRCUITS



Product specification Supersedes data of 1996 May 29 IC23 Data Handbook 1998 Feb 19





74LVT241

FEATURES

- Octal bus interface
- 3-State buffers
- Output capability: +64mA/-32mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Power-up 3-State
- Live insertion/extraction permitted
- No bus current loading when output is tied to 5V bus
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model.

QUICK REFERENCE DATA

DESCRIPTION

The 74LVT241 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

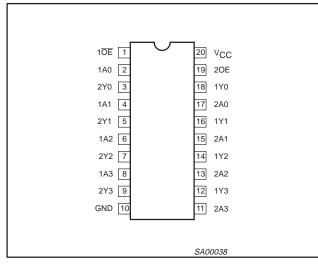
The 74LVT241 device is an octal buffer that is ideal for driving bus lines. The device features two Output Enables ($1\overline{OE}$, 2OE), each controlling four of the 3-State outputs.

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	$C_L = 50 pF;$ $V_{CC} = 3.3V$	2.8 2.8	ns
C _{IN}	Input capacitance	$V_{I} = 0V \text{ or } 3.0V$	4	pF
C _{OUT}	Output capacitance	Outputs disabled; $V_0 = 0V \text{ or } 3.0V$	8	pF
I _{CCZ}	Total supply current	Outputs disabled; $V_{CC} = 3.6V$	0.12	mA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic SOL	-40°C to +85°C	74LVT241 D	74LVT241 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74LVT241 DB	74LVT241 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVT241 PW	74LVT241PW DH	SOT360-1

PIN CONFIGURATION

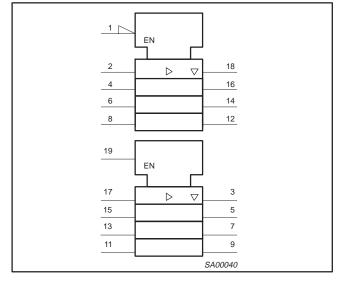


PIN DESCRIPTION

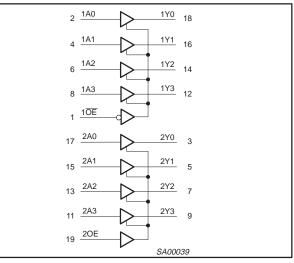
PIN NUMBER	SYMBOL	NAME AND FUNCTION		
2, 4, 6, 8	1A0 – 1A3	Data inputs		
17, 15, 13, 11	17, 15, 13, 11 2A0 – 2A3 Data inputs			
18, 16, 14, 12	1Y0 – 1Y3	Data outputs		
3, 5, 7, 9	2Y0 – 2Y3	Data outputs		
1, 19	1 <u>0E</u> , 20E	Output enables		
10	GND	Ground (0V)		
20	V _{CC}	Positive supply voltage		

74LVT241

LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



FUNCTION TABLE

	INP	OUTF	PUTS		
1 <mark>0E</mark>	1An	20E	2An	1Yn	2Yn
L	L	Н	L	L	L
L	Н	Н	н	Н	н
Н	Х	L	Х	Z	Z

H = High voltage level

L = Low voltage level

X = Don't care Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT	
V _{CC}	DC supply voltage		-0.5 to +4.6	V	
VI	DC input voltage ³		-0.5 to +7.0	V	
V _{OUT}	DC output voltage ³	Output in Off or High state	-0.5 to +7.0	V	
		Output in Low state	128		
lout	DC output current	Output in High state		mA	
I _{IK}	DC input diode current	V ₁ < 0	-50	mA	
Ι _{ΟΚ}	DC output diode current	V _O < 0	-50	mA	
T _{stg}	Storage temperature range		-65 to 150	°C	

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

NOTES:

All typical values are at T_{amb} = 25°C.
This is the increase in supply current for each input at V_{CC} –0.6V.
This parameter is valid for any V_{CC} between 0V and 1.2V with a transition time of up to 10msec. From V_{CC} = 1.2V to V_{CC} = 3.3V ± 10% a transition time of 100µsec is permitted. This parameter is valid for T_{amb} = 25°C only.
Unused pins at V_{CC} or GND

I_{CCZ} is measured with outputs pulled to V_{CC} or GND.
This is the bus hold overdrive current required to force the input to the opposite logic state.

3.3V Octal buffer/line driver (3-State)

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIN	LIMITS				
STMBOL	FARAMETER	MIN	MAX				
V _{CC}	DC supply voltage	2.7	3.6	V			
VI	Input voltage	0	5.5	V			
V _{IH}	High-level input voltage	2.0		V			
VIL	Low-level Input voltage		0.8	V			
I _{OH}	High-level output current		-32	mA			
le.	Low-level output current		32	mA			
IOL	Low-level output current; current duty cycle \leq 50%; f \geq 1kHz		64				
$\Delta t/\Delta v$	Input transition rise or fall rate; outputs enabled		10	ns/V			
T _{amb}	Operating free-air temperature range	-40	+85	°C			

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} =	-40°C to -	+85°C	UNIT
				MIN	TYP ¹	MAX	1
VIK	Input clamp voltage	V _{CC} = 2.7V; I _I = -18mA			0.9	-1.2	V
		$V_{CC} = 2.7$ to 3.6V; $I_{OH} = -100\mu A$		V _{CC} -0.2	V _{CC} -0.1		V
V _{OH}	High-level output voltage	V _{CC} = 2.7V; I _{OH} = -8mA		2.4	2.5		V
		$V_{CC} = 3V; I_{OH} = -32mA$		2	2.2		V
		V _{CC} = 2.7V; I _{OL} = 100μA			0.1	0.2	
		V _{CC} = 2.7V; I _{OL} = 24mA			0.3	0.5	1
V _{OL}	Low-level output voltage	V _{CC} = 3V; I _{OL} = 16mA			0.25	0.4	V
		$V_{CC} = 3V; I_{OL} = 32mA$			0.3	0.5	1
		$V_{CC} = 3V; I_{OL} = 64mA$		0.4	0.55	1	
		V _{CC} = 0 or 3.6V; V _I = 5.5V			1	10	
	Input leakage current	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or } GND$	Control pins		±0.1	±1	1
łı	input leakage current	$V_{CC} = 3.6V; V_{I} = V_{CC}$	Data pins ⁴		0.1	1	μA
		$V_{CC} = 3.6V; V_{I} = 0$	Data pins		-1	-5	1
I _{OFF}	Output off current	$V_{CC} = 0V$; V_{I} or $V_{O} = 0$ to 4.5V			1	±100	μΑ
		$V_{CC} = 3V; V_I = 0.8V$		75	150		
I _{HOLD}	Bus Hold current A inputs ⁶	$V_{CC} = 3V; V_I = 2.0V$		-75	-150		μA
		$V_{CC} = 0V$ to 3.6V; $V_{CC} = 3.6V$		±500			
I_{EX}	Current into an output in the High state when $V_O > V_{CC}$	V _O = 5.5V; V _{CC} = 3.0V			60	125	μA
I _{PU/PD}	Power up/down 3-State output current ³	$V_{CC} = \le 1.2V$; $V_O = 0.5V$ to V_{CC} ; $V_I = G$ OE/OE = Don't care	ND or V _{CC} ;		±1	±100	μA
I _{OZH}	3-State output High current	V _{CC} = 3.6V; V _O = 3.0V		1	5	μA	
I _{OZL}	3-State output Low current	V _{CC} = 3.6V; V _O = 0.5V			-1	-5	μA
I _{CCH}		V_{CC} = 3.6V; Outputs High, V_{I} = GND or	$V_{CC}, I_{O} = 0$		0.12	0.19	
I _{CCL}	Quiescent supply current	$V_{CC} = 3.6V$; Outputs Low, $V_I = GND$ or	V _{CC} , I _{O =} 0		3	12	mA
I _{CCZ}	1	$V_{CC} = 3.6V$; Outputs Disabled; $V_I = GN$		0.12	0.19	1	
ΔI_{CC}	Additional supply current per input pin ²	V_{CC} = 3.0 to 3.6V; One input at V_{CC} -0.0 Other inputs at V_{CC} or GND	6V;		0.1	0.25	mA

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Product specification

AC CHARACTERISTICS

GND = 0V; $t_R = t_F = 2.5ns$; $C_L = 50pF$; $R_L = 500\Omega$; $T_{amb} = -40^{\circ}C$ to +85°C.

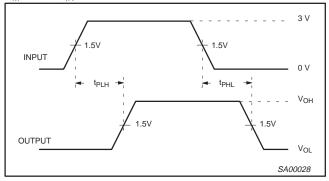
				L	IMITS		
SYMBOL	PARAMETER	WAVEFORM	T _{amb} V _C	= -40°C to + _C = +3.3V ±0.	85°C 3V	V _{CC} = 2.7V	UNIT
			MIN	TYP ¹	MAX	MAX	
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	1	1 1	2.8 2.8	3.8 3.8	4.0 4.0	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level 1OE to 1Y _n	2	1 1	3.2 3.1	4.4 4.3	5.0 4.9	ns
^t РНZ ^t PLZ	Output disable time from High and Low level 1OE to 1Y _n	2	2 1.6	3.6 2.9	5.2 4.2	5.4 4.3	ns
^t РZH ^t PZL	Output enable time to High and Low level 2OE to 2Y _n	2	1 1	3.8 3.8	5.1 5.0	5.6 5.4	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level 2OE to 2Y _n	2	1 1	3.1 2.8	4.5 4.0	5.0 4.3	ns

NOTE:

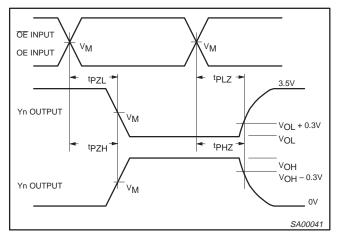
1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25^{\circ}C.

AC WAVEFORMS

 V_{M} = 1.5V, V_{IN} = GND to 3.0V



Waveform 1. Input (An) to Output (Yn) Propagation Delays

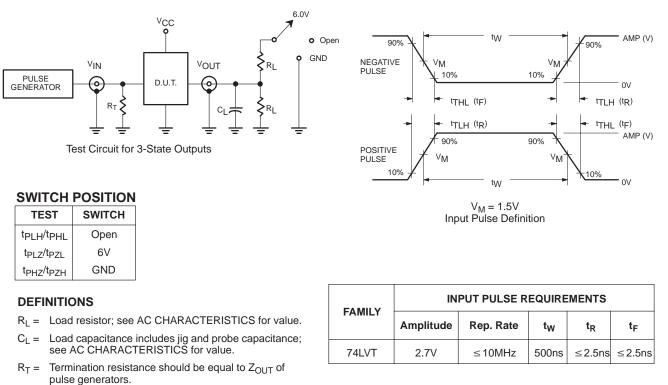


Waveform 2. 3-State Output Enable and Disable Times

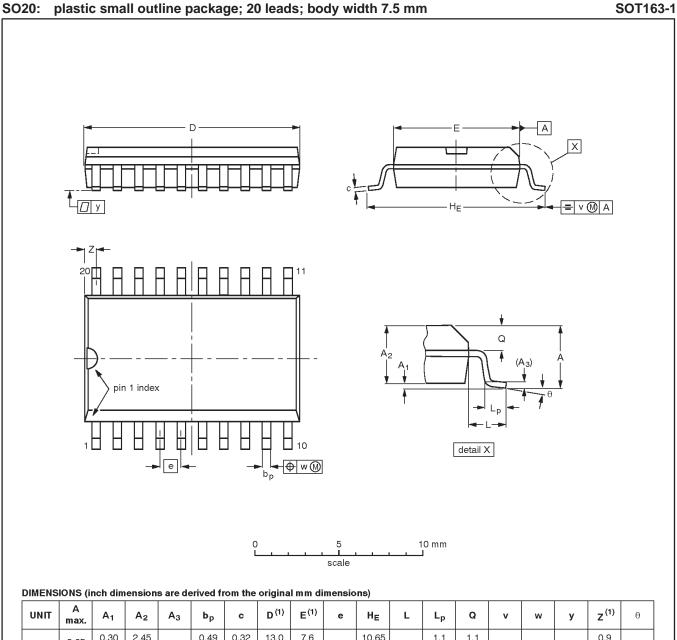
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3.3V Octal buffer/line driver (3-State)

TEST CIRCUIT AND WAVEFORMS



74LVT241



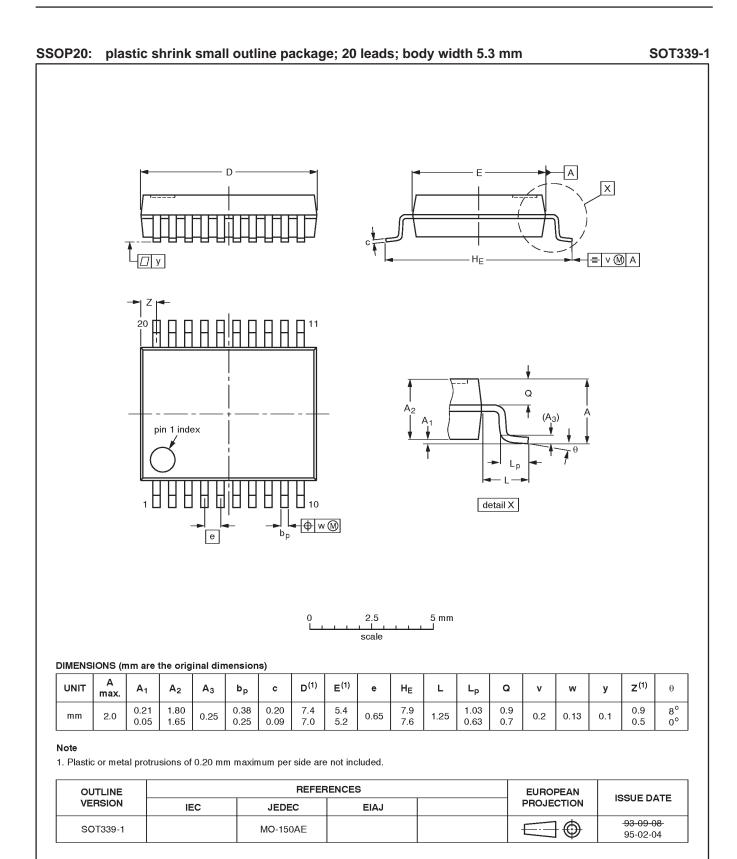
		IIIdX.	-	_	-	-					_						-	_	
r	nm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
in	ches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

Note

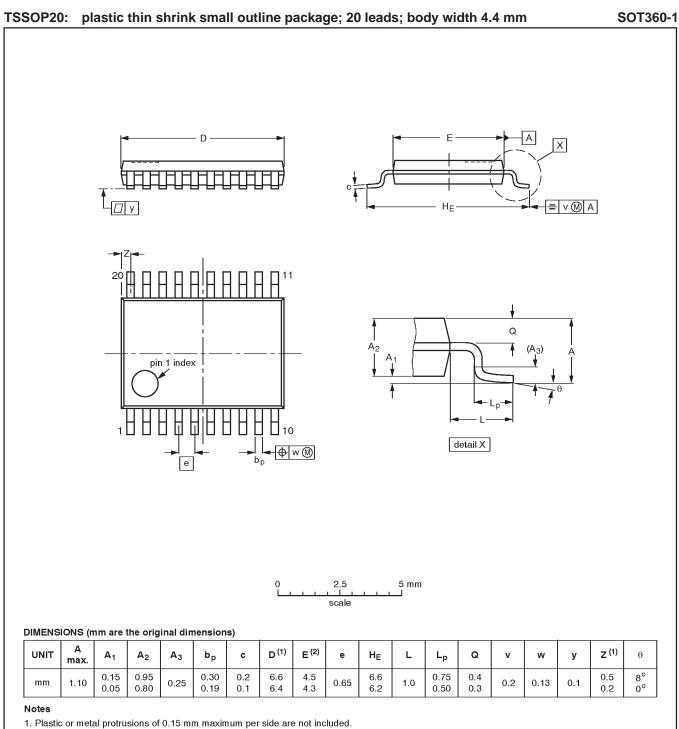
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFEF	RENCES	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE	
SOT163-1	075E04	MS-013AC				-92-11-17 95-01-24	

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2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE
SOT360-1		MO-153AC				-93-06-16 95-02-04

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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